Trench-Assisted Planar SiC MOSFET Technology



Navitas' SiC MOSFETs enabled by GeneSiC™ proprietary 'trench-assisted planar' technology provides world-leading efficiency performance over temperature, resulting in low power losses across the complete operating range. This advanced design delivers a "no-compromise" solution, balancing performance, manufacturability, and reliability in a way that traditional planar or trench SiC designs often struggle to achieve.

Over 20 Years of SiC Innovation Leadership

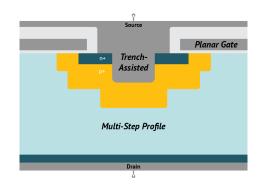
Up to 20% lower $R_{\text{DS(ON)}}$ at elevated temperature Enables lower conduction losses and cooler performance.

Up to 15% lower switching losses

Faster & efficient high frequency switching for higher power density.

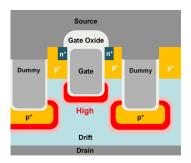
Unparalleled reliability

In high-voltage, high temperature, high humidity, high dV/dt

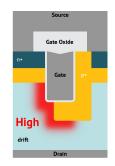


Optimized Electric Field Distribution for Enhanced Reliability and Robustness

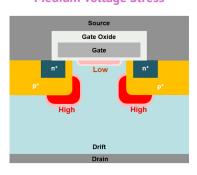
Double Trench Highest Voltage Stress



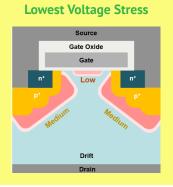
Asymmetric Trench Highest Voltage Stress



Traditional Planar Medium Voltage Stress



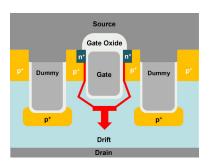
Trench-Assisted Planar Lowest Voltage Stress



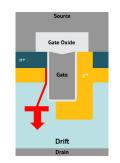
The multi-step profile in trench-assisted planar technology help to smooth out and control the electric field peaks that can occur at corners or junctions. It lowers the stress on the gate oxide and voltage across the device, resulting a long-term reliability in high-voltage, high-temperature, high-dV/dt conditions.

Optimized Current Spreading and Reduced On-Resistance at High-Temperature

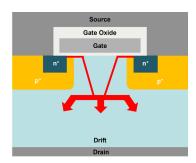
Double Trench Lowest Current Spreading



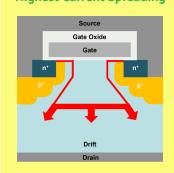
Asymmetric Trench Lowest Current Spreading



Traditional Planar Medium Current Spreading



Trench-Assisted Planar Highest Current Spreading



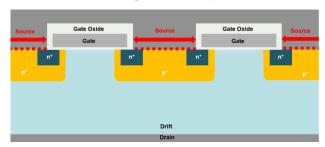
Trench-assisted planar technology demonstrates superior current spreading, a benefit attributed to the multi-step profile enabled by the trench-assist feature, resulting in lower on-resistance.

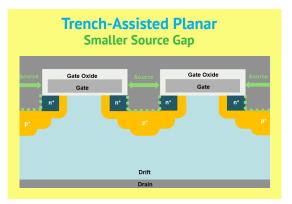




Novel Source Contact Enables Smaller Cell-Pitch and Increased Power Density

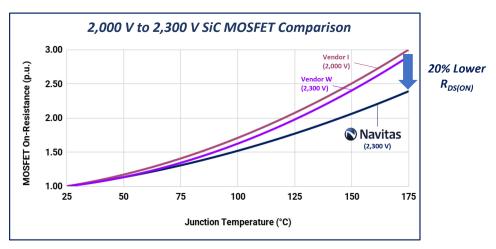
Traditional Planar Longer Source Gap





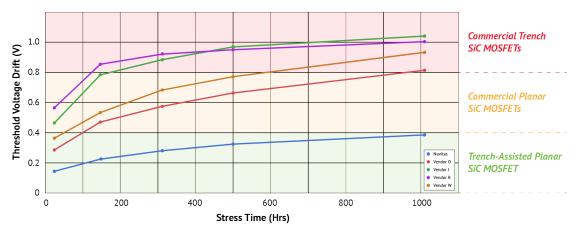
The shallow trench in the source region of trench assisted-planar design provides enough surface to have an appropriate metallization in a smaller gap, allowing for a lower cell-pitch, lowering R_{ON-SP} and $R_{ON} \times Q_G$.

Trench-Assisted Planar Technology Enables Industry's Lowest $R_{\rm DS(ON)}$ Shift vs Temperature



20% lower compared to Vendor I (2,000 V) and 17% lower than Vendor W (2,300 V)

Trench-Assisted Planar Technology Enables Industry's Lowest $V_{\text{GS(th)}}$ Shift vs Lifetime



Navitas delivers best-in-class V_{TH} stability, supporting long-term robustness and reliability for mission-critical applications requiring consistent performance over time.